NOTES:

1. ELECTRICAL CHARACTERISTICS:
   1.1. CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
   1.2. VOLTAGE RATING: 25V AC.
   1.3. INSULATION RESISTANCE: 100 MEGOHMS MIN. AT 500V DC.
   1.4. DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz,FOR 1 MINUTE.
   1.5. CONTACT RESISTANCE: 60 MILLIOHMS MAX. PER PIN INITIAL
   >30 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.

2. MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.

3. OPERATION TEMPERATURE: -55°C TO +85°C.

4. RECOMMENDED PROCESS CONDITION: SMT PEAK TEMPERATURE: 260°C 10-20S.

5. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND
**NOTES:**

1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20 mm.
2. COVER TAPE PEELING STRENGTH: 0.01 kgf MIN, 0.15 kgf MAX. AT 300mm/min.
3. PACKING CAPACITY: 310 PCS/REEL, 3 REELS/BOX, TOTAL 930 PCS/BOX.

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**ITEM DESCRIPTION**

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<th>MATERIAL</th>
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<tr>
<td>CARRIER TAPE</td>
<td>COVER TAPE</td>
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<td>AS0A82*-H2RB-7H</td>
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**DETAIL:**

- **ROUND SPROCKET HOLES**
- **EPE 1**
- **CARRIER TAPE**
- **LABEL**
- **TRANSPARENT SEAL TAPE**
- **EPE 2**
- **COVER TAPE**
- **FOLDER PAPER BOARD**
- **EPE 3**
- **WATER PROOF BAG**

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**CONNECTOR P/N:** AS0A82*-H2RB-7H

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